Specification of MEMS Microphone

(RoHS Compliance & Halogen Free)

Customer Name : Customer Model : Goermicro Model : S15OB381-068

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1 Security Warning

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2 Publication History

Version	Description	Date	Author	Approved
1.0	New Design	2020.04.02	Aaron	Rock
2.0	Update Acoustic and Electrical Characteristics Update Acoustic and Electrical	2020.09.02	Lamon	Roy
3.0	Update Acoustic and Electrical Characteristics	2021.06.22	Zamp	Jenny

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1 Introduction:

MEMS MIC which is able to endure reflow temperature up to 260° C for 50 seconds can be used in SMT process. It is widely used in telecommunication and electronics device such as mobile phone, laptop computers, and other portable electronic devices etc.

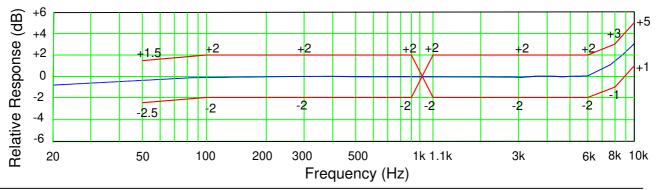
2 Test Condition (Vs=2.7V, L=50cm)

StandardConditions (As IEC 60268-4)	Temperature	Humidity	Air pressure	
Environment Conditions	+15℃~+35℃	25%R.H.~75%R.H.	86kPa \sim 106kPa	
Basic Test Conditions	+20℃ ±2℃	60%R.H.~70%R.H.	86kPa \sim 106kPa	

3 Acoustic and Electrical Characteristics

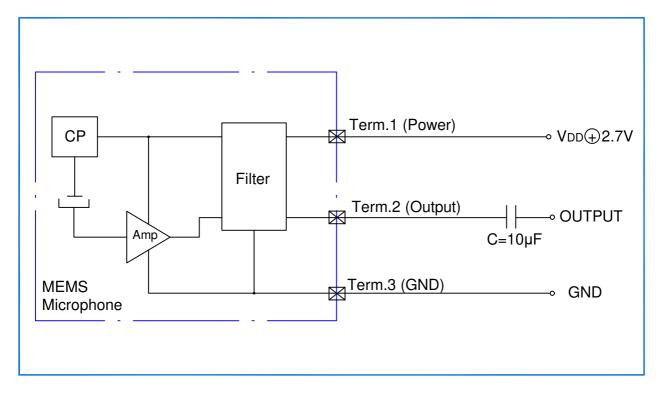
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Item	Symbol	Test Conditions	Min	Тур	Max	Unit
Operating Voltage Range	Vs		1.5	2.7	3.6	V
Current Consumption	I	Vs=2.7V			150	μA
Sensitivity	S	f=1kHz, Pin=1Pa	-39	-38	-37	dBV
S/N Ratio	SNR	f=1kHz, Pin=1Pa A-Weighted Curve		64		dB
Total Harmonic Distortion	THD	1%THD@1kHz		116		dB SPL
Acoustic Overload Point	AOP	10%THD@1kHz		128		dB SPL
Phase Response	PR	Vdd=2.7V,94dBSPL,test , Frequency 100Hz to 10Khz	-5		5	o
Power Supply Rejection	PSR	100mVpp square wave@217Hz, Vs=2.7V, A-Weighted		-96		dBV
Low Frequency Roll-off	LFRO	-3dB corner refrence to 1kHz sensitivity		10		Hz
Power Supply Rejection Ration	PSRR	200mVpp sinewave@1k Hz, Vs=2.7V		68		dB
Output Impedance	Zout	f=1kHz, Pin=1Pa			400	Ω
Decreasing Voltage Characteristic	∆s	f=1kHz, Pin=1Pa Vs=3.61.5V	No Change			
Directivity	D(θ)			Omnidire	ectional	

4 Frequency Response Curve and Limits

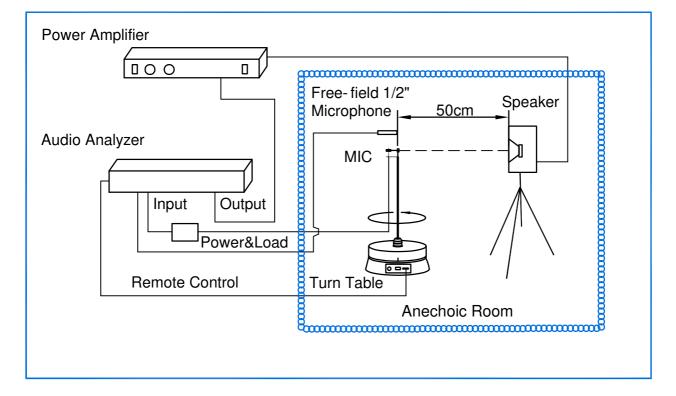




5 Measurement Circuit

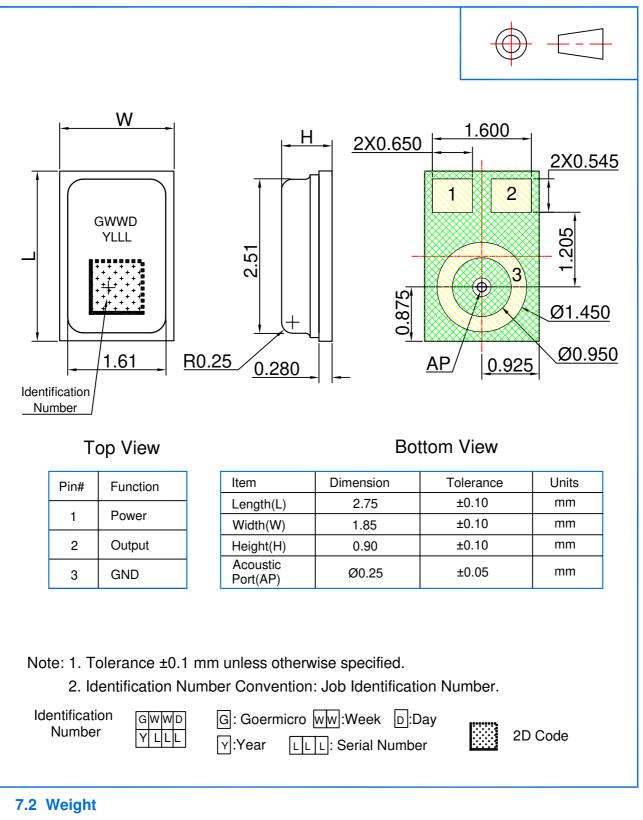


6 Test Setup Drawing



7 Mechanical Characteristics

7.1 Appearance Drawing (Unit: mm)



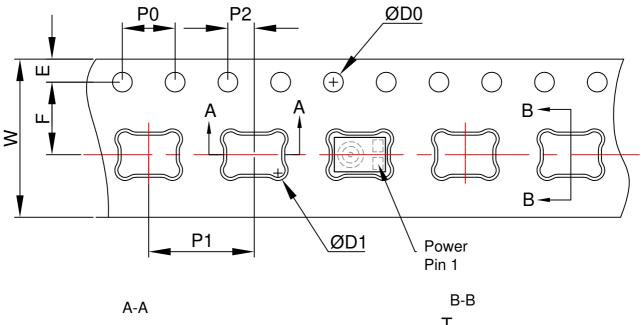
The weight of the MIC is Less than 0.02g.

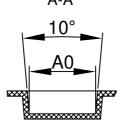
8 Reliability Test

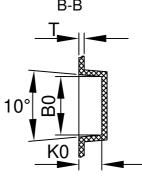
8.1 Vibration Test	To be no interference in operation after vibrations, 4 cycles, from 20 to 2,000Hz in each direction(X,Y,Z), 48 minutes, using peak acceleration of 20g, sensitivity should vary within \pm 3dB from initial sensitivity(IEC 60068-2-6:2007). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)
8.2 Drop Test	To be no interference in operation after dropped to 1.0cm steel plate 12 times from 1.5 meter height in state of JIG,JIG weight of 100g, sensitivity should vary within ±3dB from initial sensitivity(IEC60068-2-31:2008). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)
8.3 Temperature Test	 a) After exposure at +125°C for 200 hours, sensitivity should vary within ±3dB from initial sensitivity(IEC 60068-2-1:2007). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%) b) After exposure at -40°C for 200 hours, sensitivity should vary within ±3dB from initial sensitivity(IEC 60068-2-1:2007). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)
8.4 Humidity Test	After exposure at +85°C and 85% relative humidity for 200 hours, sensitivity should vary within ±3dB from initial sensitivity(IEC 60068-2-67:2019). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)
8.5 Mechanical Shock Test	Then subject samples to three one-half sine shock pulses (3000 g for 0.3 milliseconds) in each direction (for six axes in total) along each of the three mutually perpendicular axes for a total of 18 shocks, sensitivity should vary within ±3dB from initial sensitivity (IEC60068-2-27:2008). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)
8.6 Thermal Shock Test	After exposure at -40°C for 30 minutes, at +125°C for 30 minutes (change time 20 seconds) 32 cycles, sensitivity should vary within ±3dB from initial sensitivity(IEC 60068-2-14:2009). (The measurement to be done after 2 hours of condition at 15° C- 35° C, R.H. 25° \sim 75%)
8.7 Reflow Test	Adopt the reflow curve of item 12.3, after three reflows, sensitivity should vary within ±2dB from initial sensitivity(Refer to customer's request). (The measurement to be done after 2 hours of condition at 15°C-35°C, R.H. 25%~75%)
8.8 Electrostatic Discharge Test	Under C=150pF, R=330ohm. Air discharge to case with±8kV and contact discharge to I/O terminals with±2kV , 10 times, Grounding. Sensitivity should vary within ±3dB from initial sensitivity(IEC61000-4-2:2008).

9 Package

9.1 Tape Specification







The Dimensions as Follows:

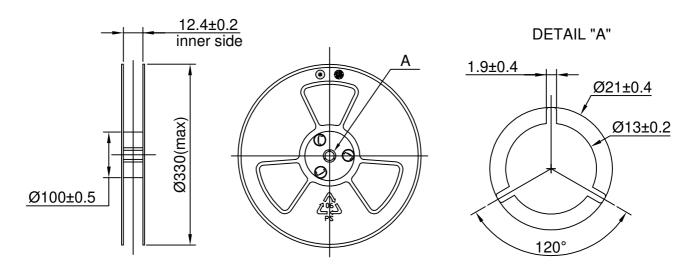
ITEM	W	E	F	ØD0	ØD1
DIM(mm)	12.0±0.30	1.75±0.10	5.5±0.05	1.50 ^{+0.10}	0.50 ^{+0.10}
ITEM	P0	10P0	P1	A0	В0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	2.95±0.05	2.05±0.05
ITEM	К0	P2	Т		
DIM(mm)	1.10±0.10	2.00±0.05	0.30±0.05		

9.2 Reel Dimension

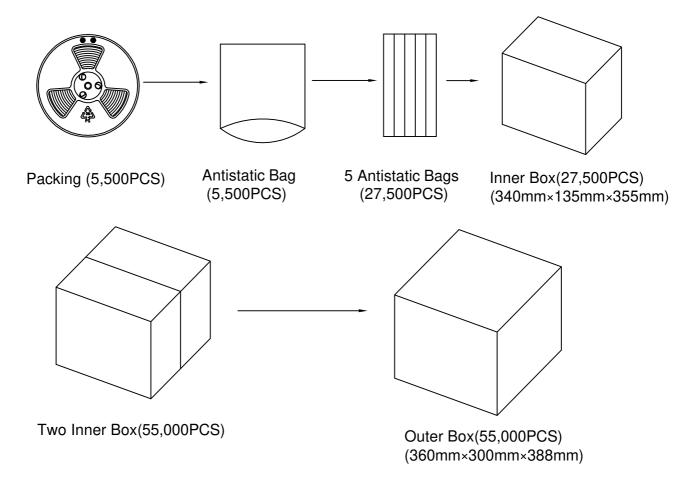
7" reel for sample stage

13" reel will be provided for the mass production stage

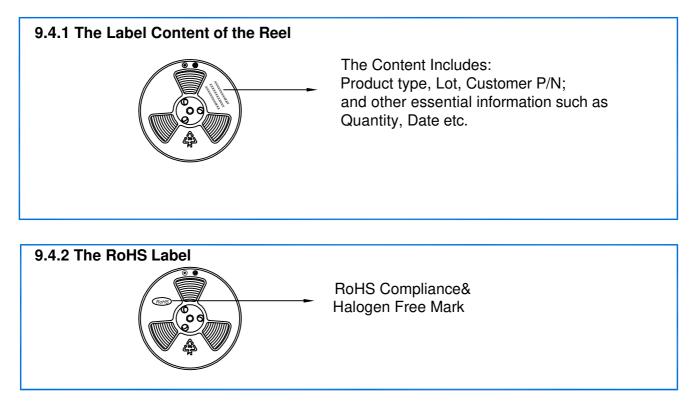
The following is 13" reel dimensions (unit:mm)



9.3 The Content of Box(13" reel)



9.4 Packing Explain



10 Storage and Transportation

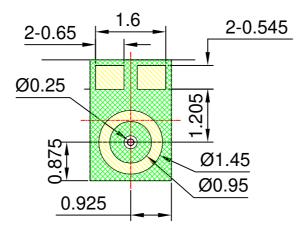
- 10.1 Keep MEMS MIC in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field. Recommend storage period no more than 1 year and floor life(out of bag) at factory no more than 4 weeks.
- 10.2 The MEMS MIC with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.
- 10.3 Storage Temperature Range: -40 $^{\circ}C \sim$ +70 $^{\circ}C$ (Microphone units with package)
- 10.4 Operating Temperature Range: -40°C~+100°C

Note1: MSL(moisture sensitivity level) Class 1(IPC/JEDEC-J-STD-020 Revision C)

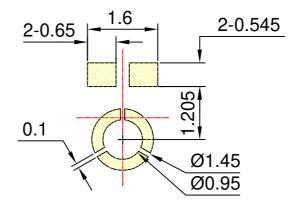
Note2: Static sensitive device

11 Land Pattern Recommendation

11.1 The Pattern of MIC Pad(Unit:mm)



11.2 Recommended Soldering Surface Land Pattern(Unit:mm)

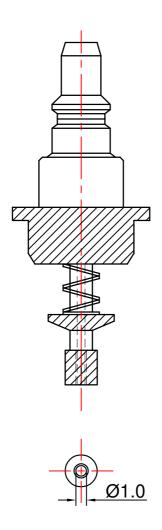


12 Soldering Recommendation

12.1 Soldering Machine Condition

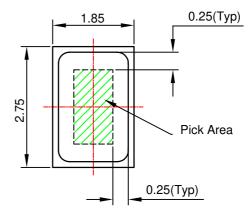
Temperature Control	8 zones	
Heater Type	Hot Air	
Solder Type	Lead-free	

12.2 The Drawing and Dimension of Nozzle

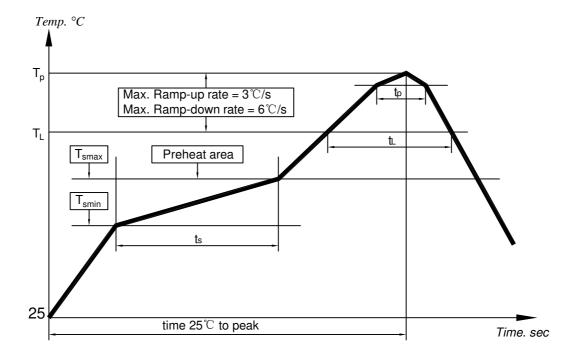


Inside Diameter: Ø1.0mm;

Please don't vacuum over the acoustic port directly. Please don't blow the acoustic port directly.



12.3 Reflow Profile



Key Features of The Profile:

Average Ramp-up rate(T_{smax} to T_p)	3℃/s max.
Preheat : Temperature Min(T _{smin}) Temperature Max(T _{smax}) Time(T _{smin} to T _{smax})(t _s)	150℃ 200℃ 60~180s
Time maintained above : Tempreature(T_L) Time(t_L)	217℃ 60~150s
Peak Temperature(T _p)	260 ℃
Time within 5 $^\circ \!\!\!\!^{\rm C}$ of actual Peak Temperature(t_p) :	30~40s
Ramp-down rate(T _p to T _{smax})	6℃/s max
Time 25 $^\circ \!$	8min max

When MEMS MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.

13 Cautions

13.1 Board Wash Restrictions

It is very important not to board wash the PCBA after reflow process, otherwise this could damage the microphone.

13.2 Vacuum Restrictions

It is very important not to put a vacuum over the acoustic port of the microphone. otherwise this could damage the microphone.

13.3 Ultrasonic Restrictions

It is very important not to use ultrasonic process. otherwise this could damage the microphone.

13.4 Air Blow Restrictions

It is very important not that o use air gun near the port hloe of the microphone, otherwise this could damage the microphone.

14 Output Inspection Standard

Output inspection standard is executed according to <<ISO2859-1:1999>>.